9 2C

8 2B

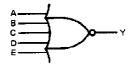
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

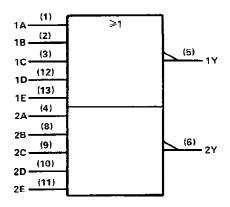
These devices contain two independent 5-input positive -NOR gates. They perform the Boolean function $Y = \overline{A + B + C + D + E}$ in positive logic.

The SN54S260 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74S260 is characterized for operation from 0°C to 70°C .

logic diagram (each gate)

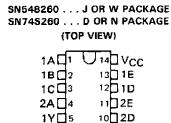


logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

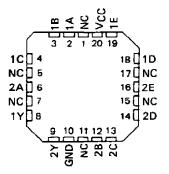
Pin numbers shown are for D, J, N, and W packages.



2Y ☐ 6

GND 7

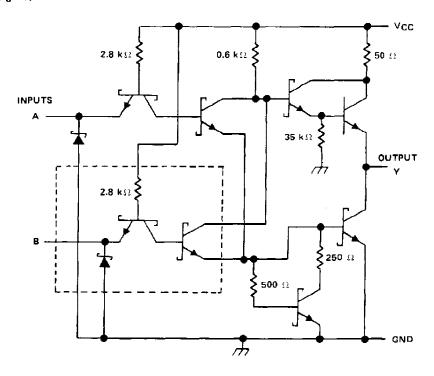
SN54S260 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

schematic (each gate)



Resistor values shown are nominal.

The portion of the schematic within the deshed-line is repeated for each additional input.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Operating free-air temperature range:	SN54'	-55°C to 125°C
-	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		7 - 9	SN54S260			SN74S260			
		MIN T	TYP	MAX	MIN	TYP	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			_ 2			V	
VIL	Low-level input voltage			8.0			0.8	V	
lон	High-level output current			- 1			- 1	mΑ	
loL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		7547.00.0	nerious t	5	N54S26	0	S	N74S26	+ MAX -1.2 4 0.5 1 1 50 -2 1	UNIT
PARAMETER		TEST CONE		MIN	түр‡	MAX	MIN	TYP [‡]	MAX	UNII
VIK	VCC = MIN,	I _I = 18 mA				-1.2			- 1.2	V
Voн	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = 1 mA	2.5	3.4		2.7	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	i _{OL} = 20 mA			0.5			0.5	V
	VCC = MAX.	V ₁ = 5.5 V	<u>-</u>			1	_		1	mA
Iн	V _{CC} = MAX,	V _{IH} = 2.7 V				50			50	μА
li L	V _{CC} = MAX,	V _{IL} = 0.5 V				– 2	""		– 2	mA
IOSS	V _{CC} = MAX			-40		- 100	- 40	_	- 100	mΑ
^I ссн	V _{CC} = MAX,	V _I = 0 V			17	29		17	29	mΑ
¹ CCL	V _{CC} = MAX,	See Note 2			26	45		26	45	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
ſ	[†] PLH	Any	>	R ₁ = 280 Ω. C ₁ = 15 pF	4	5.5	ns
	tpHL	Any	т	R _L = 280 Ω, C _L = 15 pF	4	6	пş

NOTE 3: See General Information Section for load circuits and voltage waveforms.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: One input at 4.5 V, all others at GND.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN54S260J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S260J	Samples
SN74S260D	LIFEBUY	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260	
SN74S260DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260	Samples
SN74S260N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S260N	Samples
SNJ54S260J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S260J	Samples
SNJ54S260W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S260W	Samples

(1) The marketing status values are defined as follows: ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54S260, SN74S260:

Catalog: SN74S260

Military: SN54S260

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

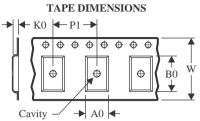
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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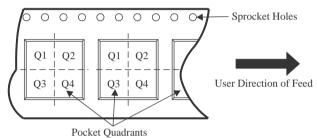
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

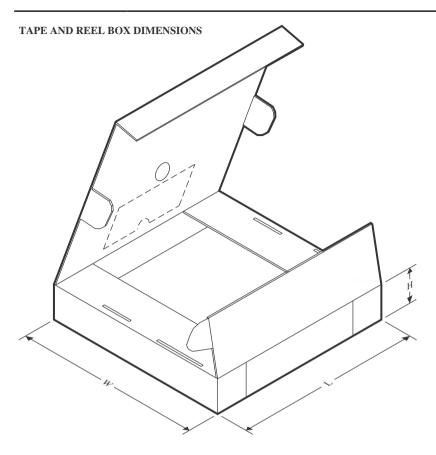


*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74S260DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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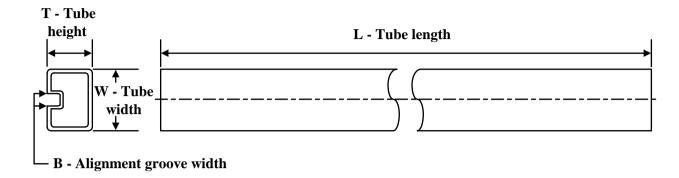
*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74S260DR	SOIC	D	14	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE

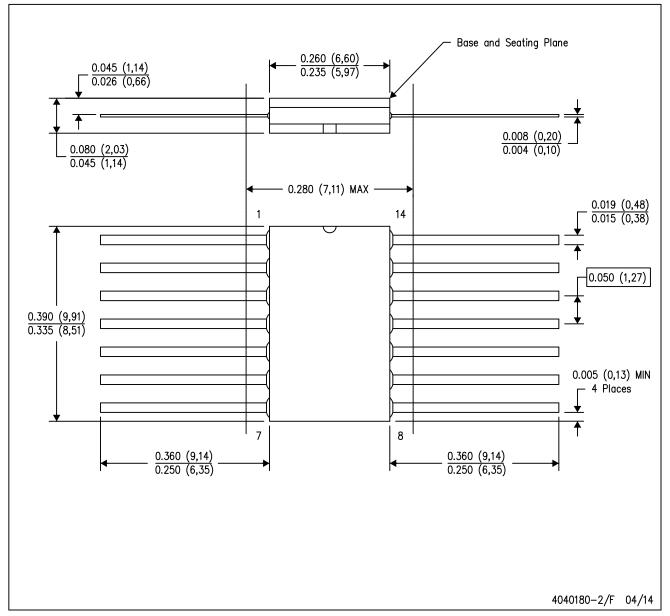


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74S260D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32

W (R-GDFP-F14)

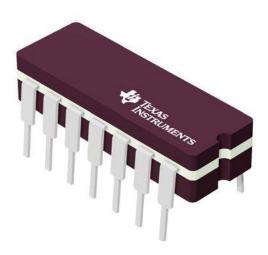
CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



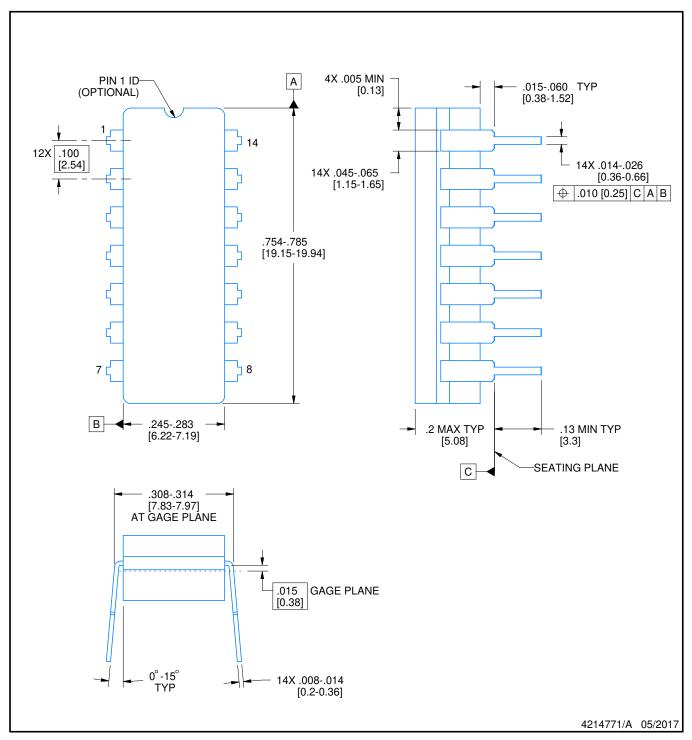
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





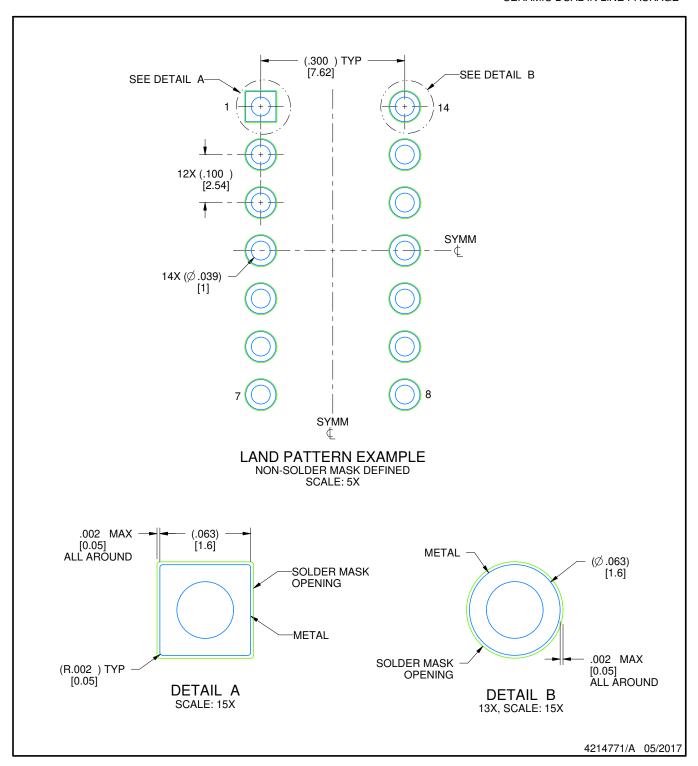
CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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